

# 2SK2590

# Silicon N Channel MOS FET

REJ03G1021-0300

(Previous: ADE-208-1365A)

Rev.3.00 Sep 07, 2005

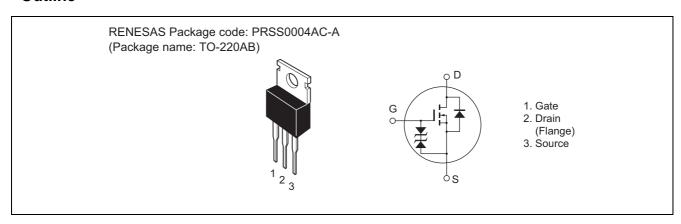
## **Application**

High speed power switching

### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

| Item                                      | Symbol                   | Ratings     | Unit |
|---|--------------------------|-------------|------|
| Drain to source voltage                   | V <sub>DSS</sub>         | 200         | V    |
| Gate to source voltage                    | V <sub>GSS</sub>         | ±20         | V    |
| Drain current                             | I <sub>D</sub>           | 7           | Α    |
| Drain peak current                        | I <sub>D(pulse)</sub> *1 | 28          | Α    |
| Body to drain diode reverse drain current | I <sub>DR</sub>          | 7           | Α    |
| Channel dissipation                       | Pch*2                    | 50          | W    |
| Channel temperature                       | Tch                      | 150         | °C   |
| Storage temperature                       | Tstg                     | -55 to +150 | °C   |

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

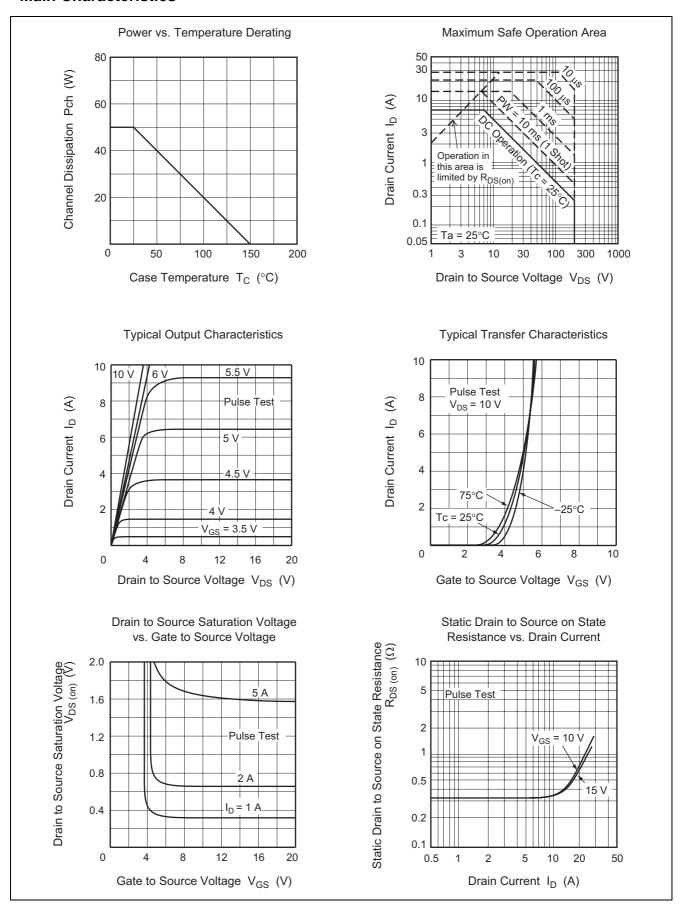
## **Electrical Characteristics**

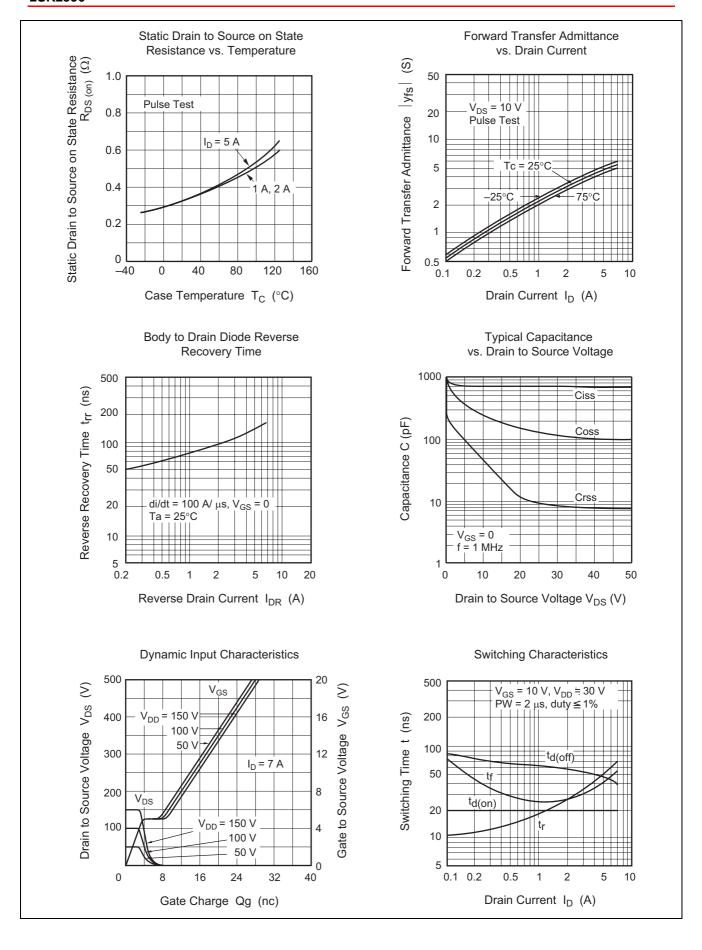
 $(Ta = 25^{\circ}C)$ 

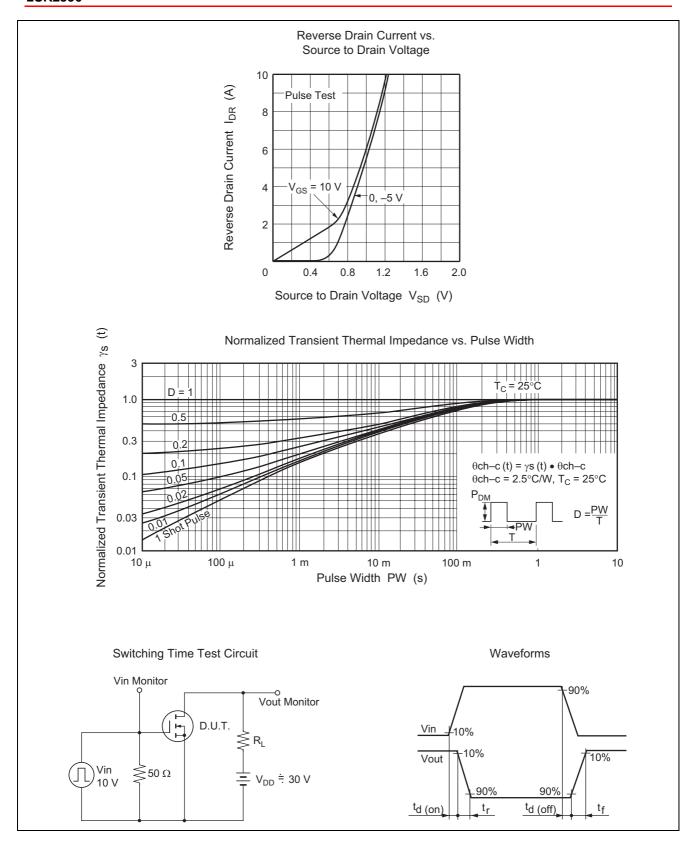
| Item                                       | Symbol               | Min | Тур  | Max  | Unit | Test Conditions                                 |  |
|--|----------------------|-----|------|------|------|---|--|
| Drain to source breakdown voltage          | V <sub>(BR)DSS</sub> | 200 | _    | _    | V    | $I_D = 10 \text{ mA}, V_{GS} = 0$               |  |
| Gate to source breakdown voltage           | V <sub>(BR)GSS</sub> | ±20 | _    | _    | V    | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$           |  |
| Gate to source leak current                | I <sub>GSS</sub>     | _   | _    | ±10  | μΑ   | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$         |  |
| Zero gate voltage drain current            | I <sub>DSS</sub>     | _   | _    | 250  | μΑ   | V <sub>DS</sub> =160 V, V <sub>GS</sub> = 0     |  |
| Gate to source cutoff voltage              | $V_{GS(off)}$        | 2.0 | _    | 4.0  | V    | $I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$     |  |
| Static drain to source on state resistance | R <sub>DS(on)</sub>  | _   | 0.33 | 0.45 | Ω    | $I_D = 4 \text{ A}, V_{GS} = 10 \text{ V*}^1$   |  |
| Forward transfer admittance                | y <sub>fs</sub>      | 3.0 | 4.5  | _    | S    | $I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$ |  |
| Input capacitance                          | Ciss                 | _   | 700  | _    | pF   | $V_{DS} = 10 \text{ V}, V_{GS} = 0,$            |  |
| Output capacitance                         | Coss                 | _   | 260  | _    | pF   | f = 1 MHz                                       |  |
| Reverse transfer capacitance               | Crss                 | _   | 45   | _    | pF   |   |  |
| Turn-on delay time                         | t <sub>d(on)</sub>   | _   | 20   | _    | ns   | $I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$     |  |
| Rise time                                  | t <sub>r</sub>       | _   | 45   | _    | ns   | $R_L = 7.5 \Omega$                              |  |
| Turn-off delay time                        | $t_{d(off)}$         | _   | 50   | _    | ns   |   |  |
| Fall time                                  | t <sub>f</sub>       | _   | 35   | _    | ns   |   |  |
| Body to drain diode forward voltage        | $V_{DF}$             | _   | 1.1  | _    | V    | $I_F = 7 \text{ A}, V_{GS} = 0$                 |  |
| Body to drain diode reverse                | t <sub>rr</sub>      | _   | 150  | _    | ns   | $I_F = 7 \text{ A}, V_{GS} = 0,$                |  |
| recovery time                              |                      |     |      |      |      | di <sub>F</sub> / dt = 100 A / μs               |  |

Note: 3. Pulse Test

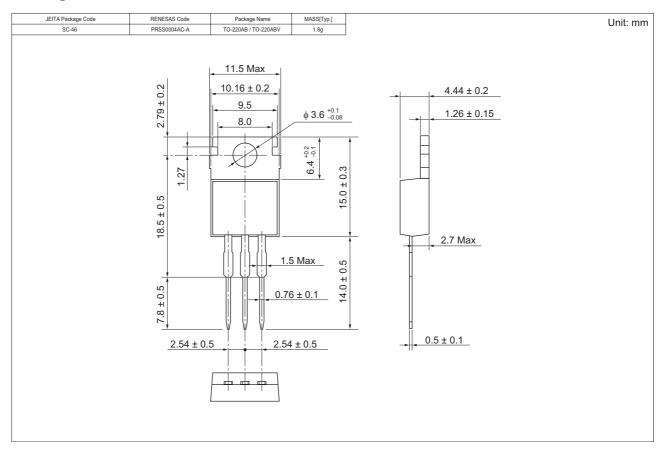
### **Main Characteristics**







# **Package Dimensions**



## **Ordering Information**

| Part Name | Quantity | Shipping Container |
|-----------|----------|--------------------|
| 2SK2590-E | 500 pcs  | Box (Sack)         |

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